

IN THE CLAIMS:

Please amend claims 1-25 as follows:

1. (Withdrawn-currently amended) A method for patterning a polymer film forming a coating on a material surface, wherein the patterning takes place by means of a stamp having a surface with at least one indentation formed therein, ~~characterized by said method comprising the steps of~~

depositing onto the material surface a thin film of polymer, and

applying to the material surface the stamp made of an elastomeric material in conformal contact with the surface of the thin film, such that portions thereof contacting one or more protruding elements of the elastomeric stamp formed by the at least one indentation thereof are attached to the protruding element or elements and removed from the material surface with the stamp.

2. (Withdrawn-Currently Amended) ~~A~~ The method according to claim 1, ~~characterized by further comprising~~ modifying the polymer film by incorporating additives in order to reduce the cohesive binding of the polymer film.

3. (Withdrawn-Currently Amended) ~~A~~ The method according to claim 2, ~~characterized by an additive being wherein one of the additives is~~ a water-soluble organic compound.

4. (Withdrawn-Currently Amended) A The method according to claim 2, characterized by an additive being wherein one of the additives is selected among from the group consisting of ethylene glycol, poly(ethylene glycol), glycerol, sorbitol, polyol, or any combinations thereof.

5. (Withdrawn-Currently Amended) A The method according to claim 1, characterized by wherein the polymer being is a water-soluble or dispersed polymer.

6. (Withdrawn-Currently Amended) A The method according to claim 1, characterized by wherein the polymer being is a conducting conjugated polymer in its doped or undoped state.

7. (Withdrawn-Currently Amended) A The method according to claim 1, characterized by wherein the polymer being is poly(3,4-dioxyethylenethiophene) (PEDOT) or deriving from a copolymer thereof or one or more mixtures incorporating the monomer (EDOT) form.

8. (Withdrawn-Currently Amended) A The method according to claim 1, characterized by further comprising modifying the material surface in order to provide a weak adhesion between the material surface and the polymer film to be removed therefrom.

9. (Withdrawn-Currently Amended) A The method, according to claim 8, ~~characterized by~~ wherein the modifying of the material surface is by plasma etching.

10. (Withdrawn-Currently Amended) A The method according to claim 1, ~~characterized by~~ further comprising modifying the elastomer stamp surface in order to provide a strong adhesion between the stamp and the polymer film to be attached thereto.

11. (Withdrawn-Currently Amended) A The method according to claim 9 10, ~~characterized by~~ wherein the modifying of the elastomer stamp surface is by plasma etching.

12. (Withdrawn-Currently Amended) A The method according to claim 1, ~~characterized by~~ further comprising enhancing the adhesion between stamp and the polymer film by means of additives to the latter.

13. (Withdrawn-Currently Amended) A The method according to claim 12, ~~characterized by~~ an additive being wherein one of the additives is glycerol.

14. (Currently Amended) A method for transferring a patterned polymer film onto a material surface by means of a stamp

having a surface with at least one indentation formed therein,  
~~characterized by~~ said method comprising the steps of

depositing onto the stamp surface a thin film of polymer,  
applying the stamp made of an elastomeric material in  
conformal contact with the material surface, such that the thin  
film of polymer is transferred thereto from one or more protruding  
elements of the elastomeric stamp formed by the at least one  
indentation thereof, and

leaving a patterned thin film of polymer on the material  
surface when removing the stamp therefrom.

15. (Currently Amended) ~~A~~ The method according to claim  
14, ~~characterized by~~ further comprising modifying the polymer film  
by incorporating additives in order to reduce the cohesive binding  
of the polymer film.

16. (Currently Amended) ~~A~~ The method according to claim  
15, ~~characterized by~~ an additive being wherein one of the additives  
is a water soluble organic compound.

17. (Currently Amended) ~~A~~ The method according to claim  
15, ~~characterized by~~ an additive being wherein one of the additives  
is selected among from the group consisting of ethylene glycol,

poly(ethylene glycol), glycerol, sorbitol, polyol, or any combinations thereof.

18. (Currently Amended) ~~A~~ The method according to claim 14, ~~characterized by~~ wherein the polymer ~~being~~ is a water-soluble or dispersed polymer.

19. (Currently Amended) ~~A~~ The method according to claim 14, ~~characterized by~~ wherein the polymer ~~being~~ is a conducting conjugated polymer in its doped or undoped state.

20. (Currently Amended) ~~A~~ The method according to claim 14, ~~characterized by~~ wherein the polymer ~~being~~ is poly(3,4-dioxyethylenethiophene) (PEDOT) or deriving from a copolymer thereof or one or more mixtures incorporating the monomer (EDOT).

21. (Currently Amended) ~~A~~ The method according to claim 14, ~~characterized by~~ further comprising modifying the elastomer stamp surface in order to provide a weak adhesion between the elastomer surface and the polymer film to be removed therefrom.

22. (Currently Amended) A The method according to claim 21, ~~characterized by~~ wherein the modifying of the elastomer stamp surface is by plasma etching.

23. (Currently Amended) A The method according to claim 14, ~~characterized by~~ further comprising modifying the material surface in order to provide a strong adhesion between the material surface and the polymer film to be transferred thereto.

24. (Currently Amended) A The method according to claim 23, ~~characterized by~~ wherein the modifying of the material surface is by plasma etching.

25. (Currently Amended) The use of a method according to claim 14 to provide a patterned etch resist in the form of a thin film of polymer on a gold layer, whereby the gold layer ~~can be~~ is removed by etching of the area unprotected by the resist, the polymer preferably being PEDOT.